

PRODUCT NUMBER

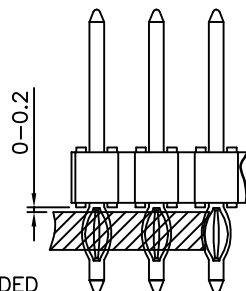
93690-YXX-XXLF

PLATING, SEE TABLE

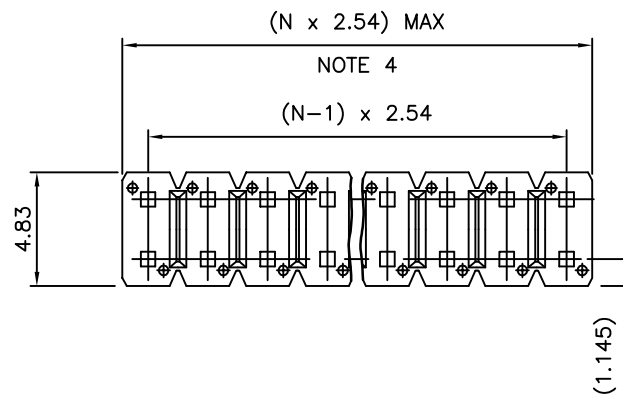
LEAD FREE
SEE NOTE 6 & 7

TOTAL NB OF POS
04 TO 72

PIN STYLE	DIM "A" REF	DIM "B" ±0.3	DIM "L" ±0.15
01	7.50	4.50	14.78
02	10.14	4.50	17.40
03	5.68	4.50	12.83
04	14.80	4.75	22.15
05	8.30	4.50	15.44
06	6.80	3.60	12.90
07	6.70	3.40	12.62
08	5.20	3.40	11.10
09	8.30	3.60	14.40
10	9.20	3.35	15.09



RECOMMENDED
POSITION ON THE PCB



DRILLED HOLE $\phi 1.15 \pm 0.025$

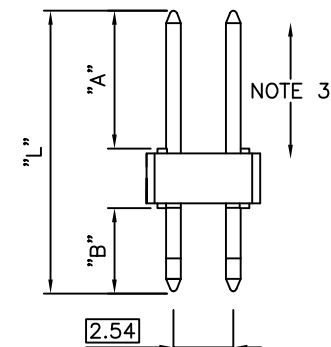
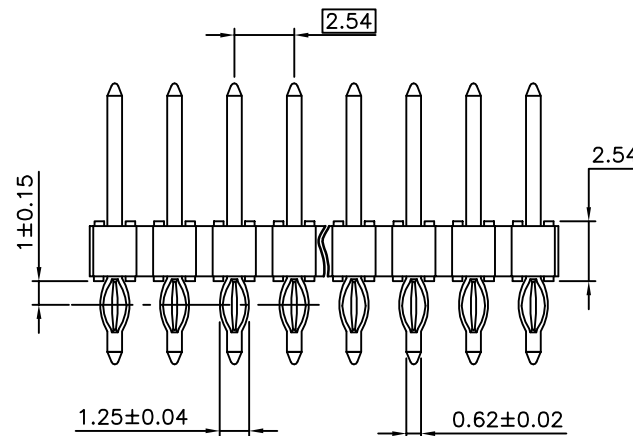
Cu 25 μ m-65 μ m

Sn 8 μ m-18 μ m

FINISHED PLATED HOLE $\phi 1^{+0.1}_{-0.05}$

NOTES:

- HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
- PIN MATERIAL : COPPER ALLOY
- 9N MIN RETENTION IN EITHER DIRECTION
- TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS PER ROW, N x 2.54 = 20.32mm
- PACKAGING POLYBAGS OR BLIBOX
- LEAD FREE CONNECTOR
- "LF" MEANS THAT THE PRODUCT IS RoHs COMPLIANT THEN MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-47-0004



93690-9XX-XXLF	0.2 μ m GOLD OVER 1.27 μ m Ni MIN	
93690-7XX-XXLF	GOLD FLASH OVER 1.27 μ m Ni MIN	1.0 μ m TIN OVER 1.27 μ m Ni MIN
93690-5XX-XXLF	0.25 μ m GOLD/GXT OVER 1.27 μ m Ni MIN	1.0 μ m TIN OVER 1.27 μ m Ni MIN
93690-4XX-XXLF	3.05 μ m TIN OVER 1.27 μ m Ni MIN	
93690-1XX-XXLF	0.76 μ m GOLD/GXT OVER 1.27 μ m Ni MIN	1.0 μ m TIN OVER 1.27 μ m Ni MIN
PLATING	CONTACT AREA	PRESS FIT TAIL AREA

mat'l. code SEE NOTE				surface ISO 1302	tolerance ISO 406 ISO 1101	projection mm	product family BSTIK
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm	title
R	B-18988	LMU	14.10.06	angles	linear		HDR PRESS FIT DOUBLE ROW
K	F08-0148	RTR	08.03.31			scale 5:1	
L	F09-0043	JCO	09.05.07	dr	MULIN.L		
M	F10-0229	LMU	10.10.04	engr	COMPAGNON J		
N	B16804	JCO	14.01.21	chr	NIZZI.P		
P	B-17404	JCO	14.04.07	appd	JM.C		
sheet index	revision	sheet					